MICRO POROUS CERAMIC HEATSINK /FCH SERIES

IC components for compact and slim electronic products are usually limited by the available space and height. The slim nature of micro porous ceramic heatsinks can provide a suitable cooling solution.

The entirely new material structure of a ceramic heatsink moves heat by air circulation (without external force) through the embedded radiation microporous ceramic material as such that the accompanying IC components can operate continuously in a given temperature environment.

The unique material properties of the ceramic heat sink allows it be non-electrically conductive, and also heat and dust proof. With a long-life span and simple assembly process (simply place it to the surface of any IC component), a ceramic heat sink saves not only assembly time but also material and labour costs.

Ceramic heat sinks are now adopted by IC of power under 10W while specially designed ones are also available for high-watt ICs.

Part Number	Length (mm)	Width (mm)	Height (mm)	Shape
FCH252505T	25	25	5.0	Fin
FCH30305T	30	30	5.25	Fin
FCH303512T	35	30	12.25	Fin
FCH40405T	40	40	5.25	Fin
FCH505010T	50	50	10.25	Fin
FCH505015T	50	50	15.25	Fin

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